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Applicant(s): Tabrizi, B.
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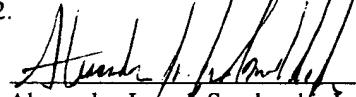
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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231 on February 15, 2002.



Alexander Joseph Smolenski, Jr.

Commissioner for Patents
Washington, D.C. 20231

Response to Outstanding Office Action

Dear Sir:

In response to the Office Action mailed October 18, 2001, Applicant respectfully requests consideration of the following amendments and remarks.

In the Claims:

Please amend claims 2, 3, 7, 9, 14, 34, and 35 as follows:

B1 2. An electronic component according to claim 1, wherein:
the conductive region is formed by metallization.

3. An electronic component according to claim 2, wherein:
the metallization is achieved through a deposition process.

B2 7. An electronic component according to claim 1, further comprising: